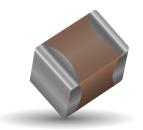
X7S Dielectric

General Specifications





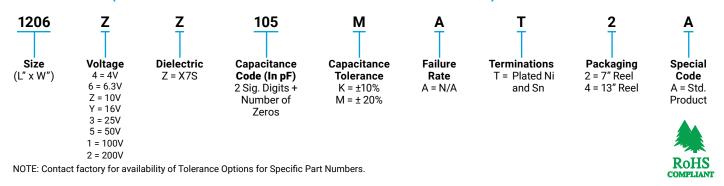
GENERAL DESCRIPTION

X7S formulations are called "temperature stable" ceramics and fall into EIA Class II materials. Its temperature variation of capacitances within $\pm 22\%$ from -55° C to $\pm 125^{\circ}$ C. This capacitance change is non-linear.

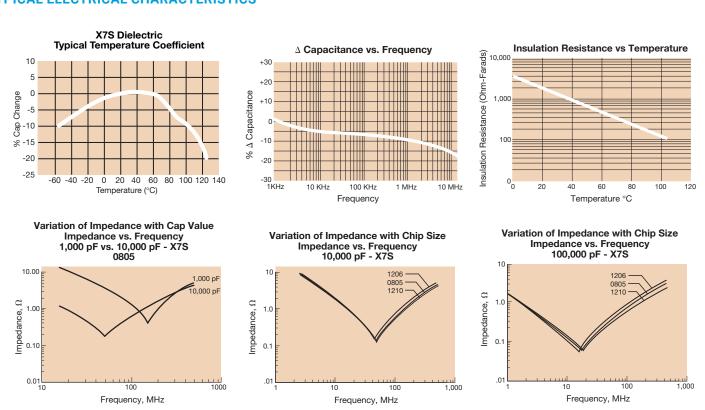
Capacitance for X7S varies under the influence of electrical operating conditions such as voltage and frequency.

X7S dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



TYPICAL ELECTRICAL CHARACTERISTICS



X7S Dielectric

Specifications and Test Methods



Parame	ter/Test	X7S Specification Limits	Measuring Conditions					
	perature Range	-55°C to +125°C	Temperature Cycle Chamber					
	on Factor	Within specified tolerance ≤ 5.0% for ≥ 100V DC rating ≤ 5.0% for ≥ 25V DC rating ≤ 10.0% for ≥ 10V DC rating ≤ 10.0% for ≤ 10V DC rating Contact Factory for DF by PN	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 µF, 0.5Vrms @ 120Hz					
Insulation	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity					
Dielectric	: Strength	No breakdown or visual defects	Charge device with 250% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)					
	Appearance	No defects		Deflection: 2mm				
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 30 seconds 1mm/sec					
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)	90 mm					
	Insulation Resistance	≥ Initial Value x 0.3						
Solderability		≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.					
	Appearance	No defects, <25% leaching of either end terminal						
	Capacitance Variation	≤ ±7.5%	5					
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2					
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	hours before measuring electrical properties.				
	Dielectric Strength	Meets Initial Values (As Above)						
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes				
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes				
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes				
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes				
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro	and measure after oom temperature				
	Appearance	No visual defects						
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 rated voltage (≤ 10V) in test chamber set at 125°C ± 2°C for 1000 hours (+48, -0) Remove from test chamber and stabilize at room temperature for 24 ± 2 hours before measuring.					
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)						
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)						
	Dielectric Strength	Meets Initial Values (As Above)						
	Appearance	No visual defects						
	Capacitance Variation	≤ ±12.5%		per set at 85°C ± 2°C/ 85% ± midity for 1000 hours				
Load	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated					
Humidity	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber and stabilize at room temperature and humidity for					
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours bef	ore measuring.				

X7S Dielectric

Capacitance Range



PREFERRED SIZES ARE SHADED

		-		E	ш						
SIZE			402	0603	0805		1206		1210		
Solder		Reflow/Wave		Reflow/Wave	Reflow/Wave	Reflow/Wave			Reflow Only		
Packag	ging	All Paper		All Paper	Paper/Embossed	Paper/Embossed			Paper/Embossed		
(L) Length	mm	1.00 ± 0.10 (0.040 ± 0.004)		1.60 ± 0.15	2.01 ± 0.20	3.20 ± 0.20			3.20 ± 0.20		
(L) Length	(in.)			(0.063 ± 0.006)	(0.079 ± 0.008)		(0.126 ± 0.008)		(0.126 ± 0.008)		
W) Width	mm		0.50 ± 0.10		1.25 ± 0.20	1.60 ± 0.20			2.50 ± 0.20		
	(in.)		± 0.004)	(0.032 ± 0.006)	(0.049 ± 0.008)	(0.063 ± 0.008)			(0.098 ± 0.008)		
(t)	mm		± 0.15	0.35 ± 0.15	0.50 ± 0.25		0.50 ± 0.25 (0.020 ± 0.010)		0.50 ± 0.25		
Terminal	(in.)		± 0.006)	(0.014 ± 0.006)	(0.020 ± 0.010)				(0.020 ± 0.010)		
	WVDC	4	6.3	6.3	4	10	10 50 10		6.3		
Сар	100										
(pF)	150										
	220					,	_		- W		
	330								VV-		
	470					*		_)) [
	680					. (7	$\mathcal{V} \stackrel{\downarrow}{\leftarrow} -$		
	1000 1500					· '	_	ヿレ			
	2200							\smile			
	3300					}		t			
							il.	, ,	ı		
	4700										
	6800										
Cap	0.010										
(μF)	0.015										
	0.022										
	0.033		С								
	0.047		С								
	0.068		С								
	0.10		С								
	0.15										
	0.22										
	0.33			G							
	0.47			G							
	0.68			G							
	1.0	Е		G							
	1.5	-			N						
<u> </u>	2.2	Е			N						
	3.3				N						
	4.7				N	Q					
	10 22								Z		
									L		
	47										
-	100	4	6.2	6.0	4	10	FO	100	6.0		
	WVDC SIZE	4 6.3 0402		6.3 0603	4 0805	10 50 100 1206			6.3 1210		
	SIZE	U	402	0003	0800		1200		1210		

Letter	Α	С	Е	G	J	K	М	N	Р	Q	Х	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.90	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.075)	(0.090)	(0.100)	(0.110)
	PAPER					EMBOSSED							

^{*}Contact Factory for Specifications